

IN THE SPECIFICATION

Applicant is concurrently submitting a copy of the parent's clean substitute specification.  
Please amend that specification as follows.

Please change the title as follows--

METHOD AND APPARATUS FOR COATING OF A SEMICONDUCTOR WAFER A  
WAFER

--.

**[0001]** This application is a continuation of U.S. App. Ser. No. 10/155,450, filed May 22, 2002; which is a divisional of U.S. App. Ser. No. 09/292,081, filed Apr. 14, 1999; 1999 and issued as U.S. Pat. No. 6,423,380; which is a continuation of U.S. App. Ser. No. 08/949,072, filed Oct. 10, 1997 and issued as U.S. ~~Patent~~Pat. No. 5,902,399; which is a continuation of U.S. App. Ser. No. 08/508,051, filed Jul. 27, 1995, and now abandoned.